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Interested committees:

Title: BS EN IEC 63567-1 Semiconductor devices - Performance evaluation of semiconductor processing components and inspection equipment

Part 1: Transmittance evaluation method of EUV pellicle

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	

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IEC TC 47 : SEMICONDUCTOR DEVICES		
SECRETARIAT: Korea, Republic of		SECRETARY: Mr Cheolung Cha
OF INTEREST TO THE FOLLOWING COMMITTEES:		HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:		

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TITLE:

Semiconductor devices - Performance evaluation of semiconductor processing components and inspection equipment - Part 1: Transmittance evaluation method of EUV pellicle

NOTE FROM TC/SC OFFICERS:

The title was changed from "Semiconductor devices - Performance evaluation of semiconductor components and equipment - Part 1: Transmittance evaluation method of EUV pellicle" to "Semiconductor devices - Performance evaluation of semiconductor processing components and inspection equipment - Part 1: Transmittance evaluation method of EUV pellicle"

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES -
PERFORMANCE EVALUATION OF SEMICONDUCTOR PROCESSING
COMPONENTS AND INSPECTION EQUIPMENT****Part 1: Transmittance evaluation method of EUV pellicle****FOREWORD**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.